



# SOT1747-1

HSOP54, plastic, thermal enhanced small outline package; 54 terminals; 0.65 mm pitch; 7.5 mm x 17.9 mm x 2.22 mm body

1 October 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	HSOP54
<b>Package style descriptive code</b>	HSOP (heatsink small outline package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	02-03-2016
<b>Manufacturer package code</b>	98ARL10519D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	17.9	-	mm
package width	-	7.5	-	mm
package height	-	2.22	-	mm
nominal pitch	-	0.65	-	mm
actual quantity of termination	-	54	-	



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2 Package outline

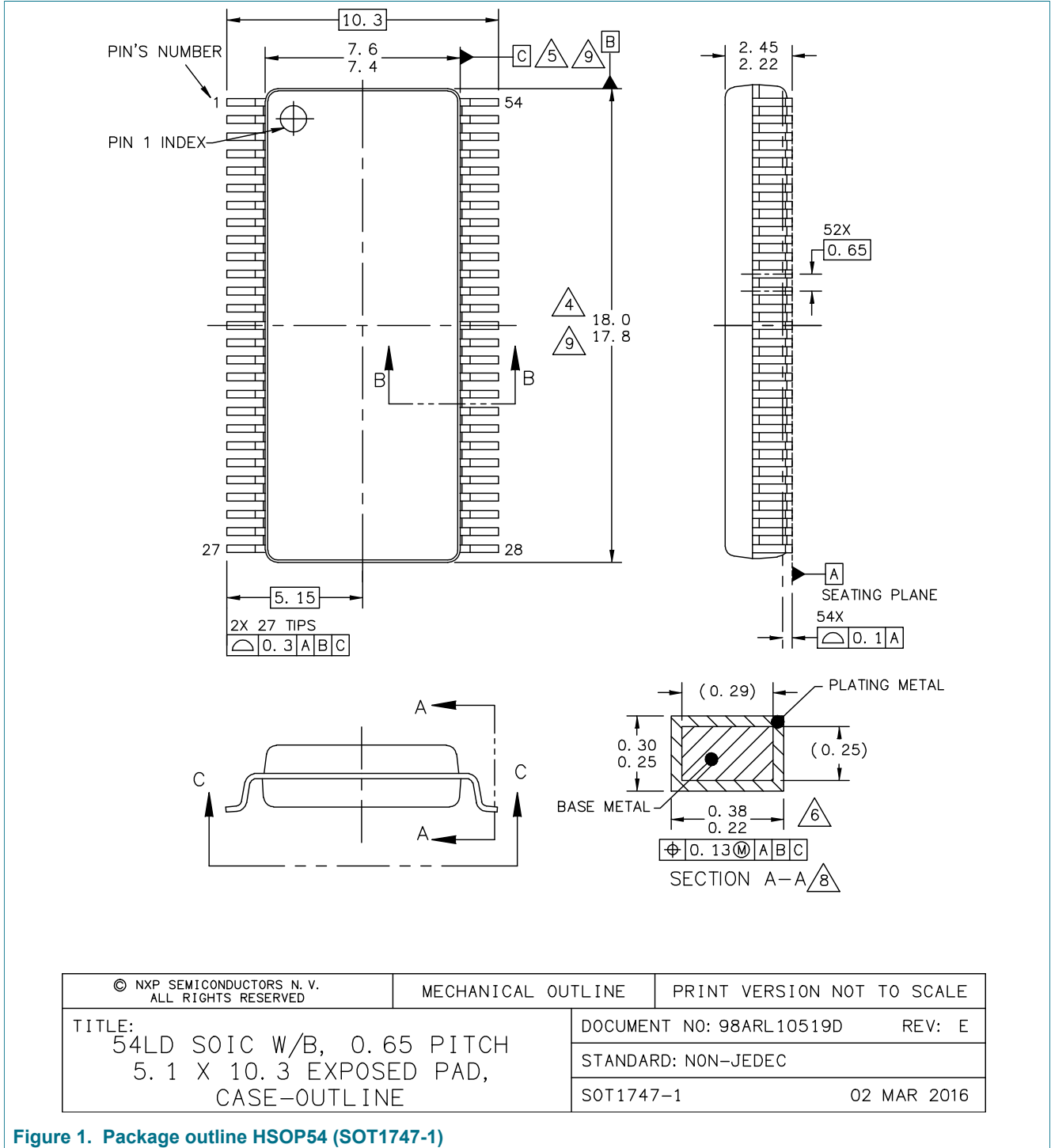


Figure 1. Package outline HSOP54 (SOT1747-1)

HSOP54, plastic, thermal enhanced small outline package; 54 terminals; 0.65 mm pitch; 7.5 mm x 17.9 mm x 2.22 mm body

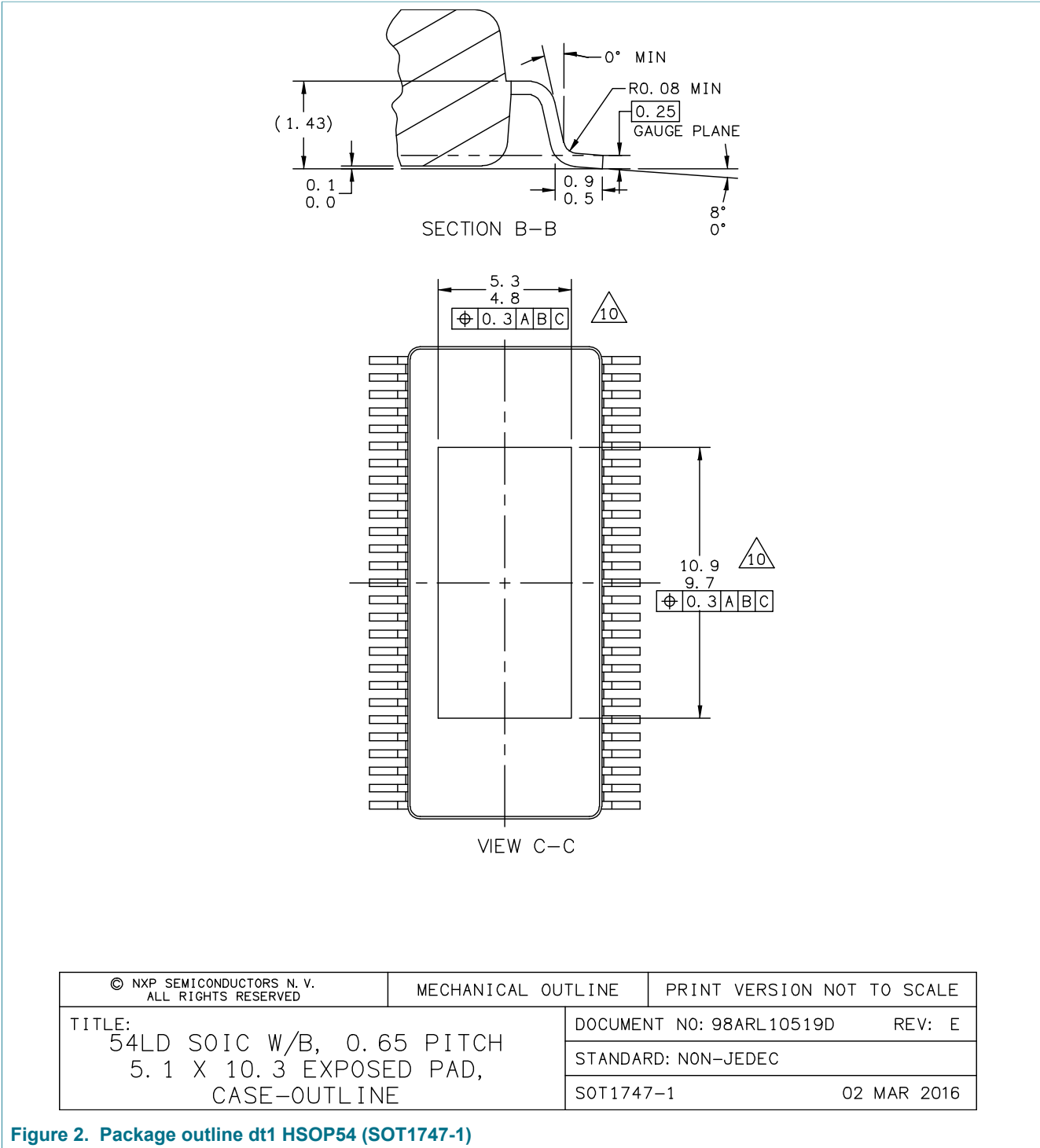


Figure 2. Package outline dt1 HSOP54 (SOT1747-1)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS B AND C TO BE DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
4. THIS DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSION OR GATE BURRS. MOLD FLASH, PROTRUSION OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
5. THIS DIMENSION DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED 0.25 MM PER SIDE. THIS DIMENSION IS DETERMINED AT THE PLANE WHERE THE BOTTOM OF THE LEADS EXIT THE PLASTIC BODY.
6. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.46 mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 mm.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 mm AND 0.3 mm FROM THE LEAD TIP.
9. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM. THIS DIMENSION IS DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTER-LEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
10. THESE DIMENSIONS RANGES DEFINE THE PRIMARY KEEP-OUT AREA. MOLD LOCKING AND RESIN BLEED CONTROL FEATURES MAY BE VISIBLE AND THEY MAY EXTEND TO 0.4mm FROM MAXIMUM EXPOSED PAD SIZE

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TITLE: 54LD SOIC W/B, 0.65 PITCH 5.1 X 10.3 EXPOSED PAD, CASE-OUTLINE	DOCUMENT NO: 98ARL10519D	REV: E
	STANDARD: NON-JEDEC	
	SOT1747-1	02 MAR 2016

Figure 3. Package outline note HSOP54 (SOT1747-1)

### 3 Legal information

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Contents

1 Package summary .....1  
2 Package outline .....2  
3 Legal information .....5